

Memory Product Specification

ES.16G2Z.GGE

16GB 2G x 64

DDR4-3000MHz CL18 Overclocking SO-DIMM

Description:

The overclocking SO-DIMM for 2G x 64 of 16GB DDR4-3000MHz CL18-20-20-38 at 1.2V Memory Module.

The Module base on sixteen 1024M x 8 DDR4 FBGA SDRAM components.

The SPDs are programmed to JEDEC standard latency DDR4-2133MHz of CL15-15-15 at 1.2V.

Memory Module intended for mounting into 260-pin edge connector sockets.

The electrical and mechanical specifications are as follows:

Features:

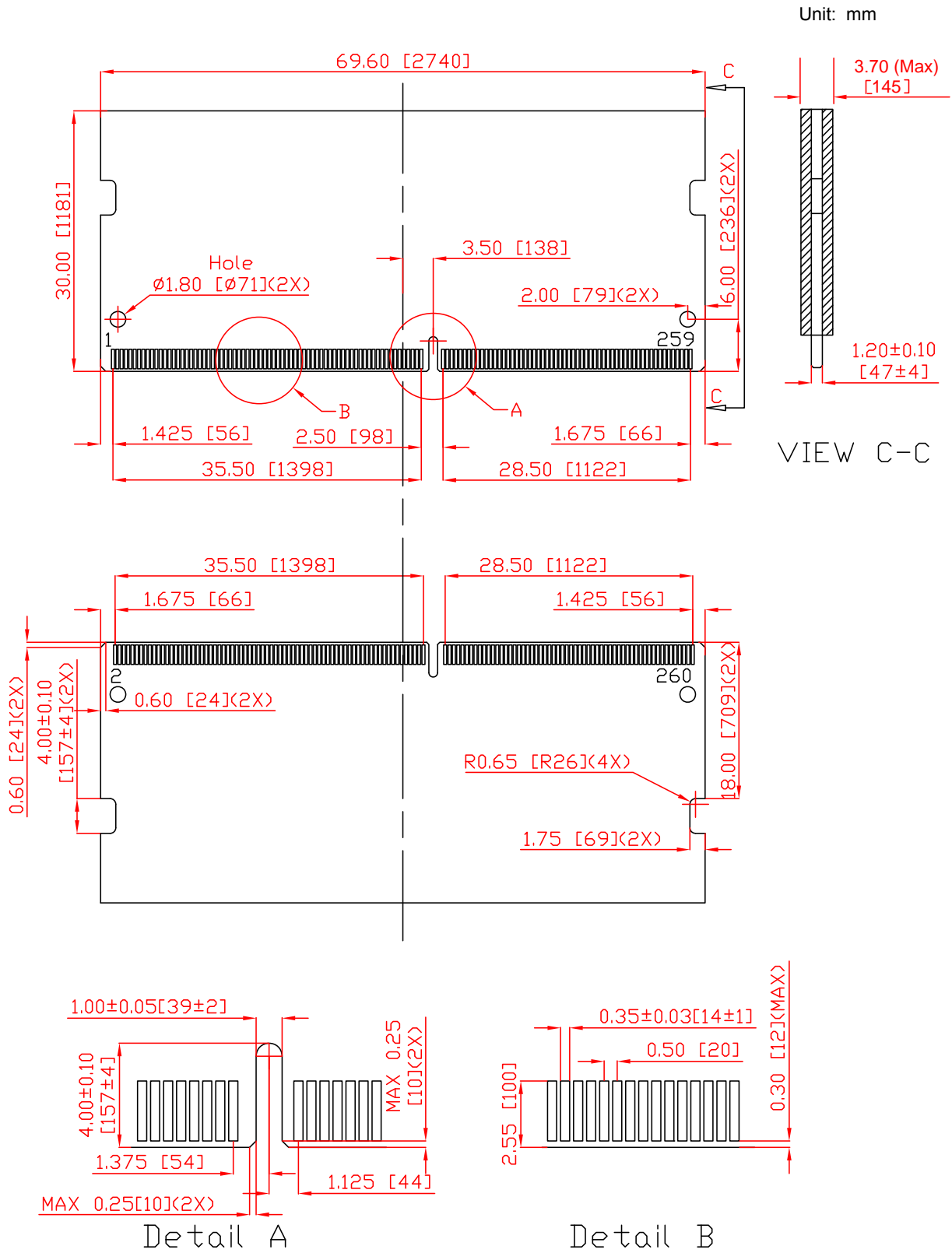
- DDR4 Speed Grade : 2133Mbps
- Organization
 - 2G x 64, 2 ranks
- Mounting 16 pieces of 8G bits DDR4 SDRAM sealed in FBGA
- Package: 260-pin socket type small outline dual in-line memory module (SO-DIMM)
 - PCB height: 1.181 inch (30.00 mm)
 - Lead-free (RoHS compliant)
 - Halogen free
- Power supply: VDD = 1.2V (1.14V to 1.26V)
- 16 internal banks (4 Bank Groups)
- Burst lengths (BL): 8 and 4 with Burst Chop (BC)
- Precharge: auto precharge option for each burst access

- Refresh: auto-refresh, self-refresh
- Refresh cycles
 - Average refresh period
 - 7.8 μ s at $0^{\circ}\text{C} \leq \text{TC} \leq +85^{\circ}\text{C}$
 - 3.9 μ s at $+85^{\circ}\text{C} < \text{TC} \leq +95^{\circ}\text{C}$
- Operating case temperature range
 - TC = 0°C to $+95^{\circ}\text{C}$

Overclocking Datasheet w/ Intel XMP:

- DDR4 Speed Grade : 3000Mbps
- Power supply: VDD Voltage : 1.2V
VDDQ Voltage: 1.2V
- CAS latency : CL18-20-20-38
- Bandwidth : 24000MB/s
- Serial presence detect with EEPROM.
- PCB height : 1.181 inch (30.00 mm)
- RoHS Compliant
- Halogen free
- Application : Gaming player

Dimensions



(All dimensions are in millimeters with ± 0.15 mm tolerance unless specified otherwise.)